

AMENDMENTS TO THE ABSTRACT:

Please amend the ABSTRACT as follows:

ABSTRACT

Chip carrier with integrated functions such as antennas, EMI shields, and heat sinks are formed of a conductive loaded resin-based material. The conductive loaded resin-based material comprises micron conductive powder(s), conductive fiber(s), or a combination of conductive powder and conductive fibers in a base resin host. The ratio of the weight of the conductive powder(s), conductive fiber(s), or a combination of conductive powder and conductive fibers to the weight of the base resin host is between about 0.20 and 0.40. The micron conductive powders are formed from non-metals, such as carbon, graphite, that may also be metallic plated, ~~or the like,~~ or from metals such as stainless steel, nickel, copper, silver, that may also be metallic plated, ~~or the like,~~ or from a combination of non-metal, plated, or in combination with, metal powders. The micron conductor fibers preferably are of nickel plated carbon fiber, stainless steel fiber, copper fiber, silver fiber, or the like. ~~The conductive loaded resin-based integrated chip carrier functions can be formed using methods such as injection molding~~

~~compression molding or extrusion. The conductive loaded resin-~~
~~based material used to form the integrated chip carrier~~
~~functions can also be in the form of a thin flexible woven~~
~~fabric that can readily be cut to the desired shape.~~